	Input Power Dissipation	P_D	100	mW
Output	Supply Voltage	V_{CC}	7	V
	Output Voltage	V_O	V_{CC}+0.5	V
	Output Current	I_O	10	mA
	Output Power Dissipation	P_O	22	mW
Total Power Dissipation		P_{tot}	130	mW
Isolation Voltage		V_{iso}	3750	Vrms
Operating Temperature		T_{opr}	-40~110	
Junction Temperature		T_j	125	
Storage Temperature		T_{stg}	-55~125	
Soldering Temperature		T_{sol}	260	

: μ

:

(Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	I_F=10mA	-	1.35	1.6	V
	Input Reverse Breakdown Voltage	BV_R	I_R=10μA	5	-	-	V
	Reverse Current	I_R	V_R=6V	-	-	1	μA
	Input Capacitance	C					
Output	W=0,f=1MHz 30 Supply Current	100 I_{CCH}	pF V_{CC}=5V,I_F=0mA	-	-	6.5	mA
	Low Level Supply Current	I_{CCL}	V_{CC}=5V,I_F=10mA	-	-	6.5	mA
	Logic HOutput Voltage	V_{OH}	I_F=0mA,I_O=-20μA	$V_{DD-0.1}$	V_{DD}	-	V
	Logic Low Output Voltage	V_{OL}	I_F=7mA,I_O=20μA, V_{CC}=5V	-	0.02	0.1	V
	Isolation Resistance	R_{ISO}	DC500V 40~60%R.H	10^{12}	-	-	Ω
	Floating Capacitance	C_{IO}		-	0.6	-	pF
Switching Characteristics	Trigger LED Current	I_{FT}	V_{CC}=5V	-	-	5	mA

	Propagation Delay Time to Logic Low	TPHL	I_F=7mA,C_L=15pF	-	70	100	ns
	Propagation Delay Time to Logic High	TPLH	I_F=7mA,C_L=15pF	-	55	100	ns
	Common Mode Transient Immunity at Logic High	CM_H	I_F=0mA, V_{CM}=1000Vpp, C_L=15pF, V_{CC}=5V	20	-	-	kV/μs
	Common Mode Transient Immunity at Logic Low	CM_L	I_F=7mA, V_{CM}=1000Vpp, C_L=15pF, V_{DD}=5V	20	-	-	kV/μs

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Operating Temperature	T_a	-40	-	105	
Supply Voltage	V_{CC}	2.7	-	5.5	V
Low Level Input Current	I_{FL}	0	-	250	μA
High Level Input Current	I_{FH}	8	-	16	mA
Forward Voltage	$V_{F(OFF)}$	-	-	0.8	V

JOCHC15B

JOCHC15B

FIG.7: Propagation Delay vs. Ambient Temperature

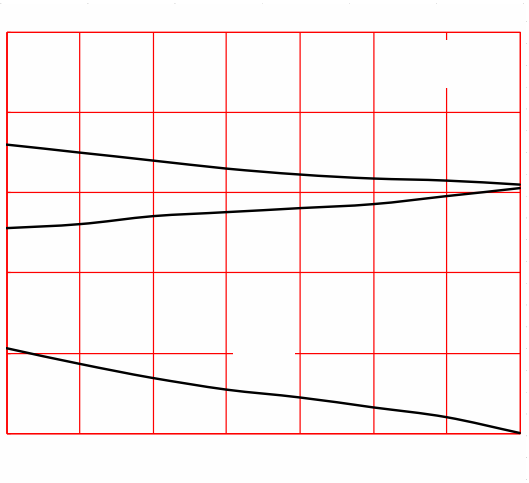
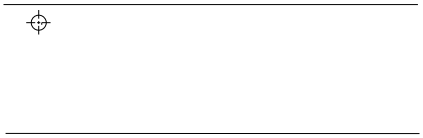
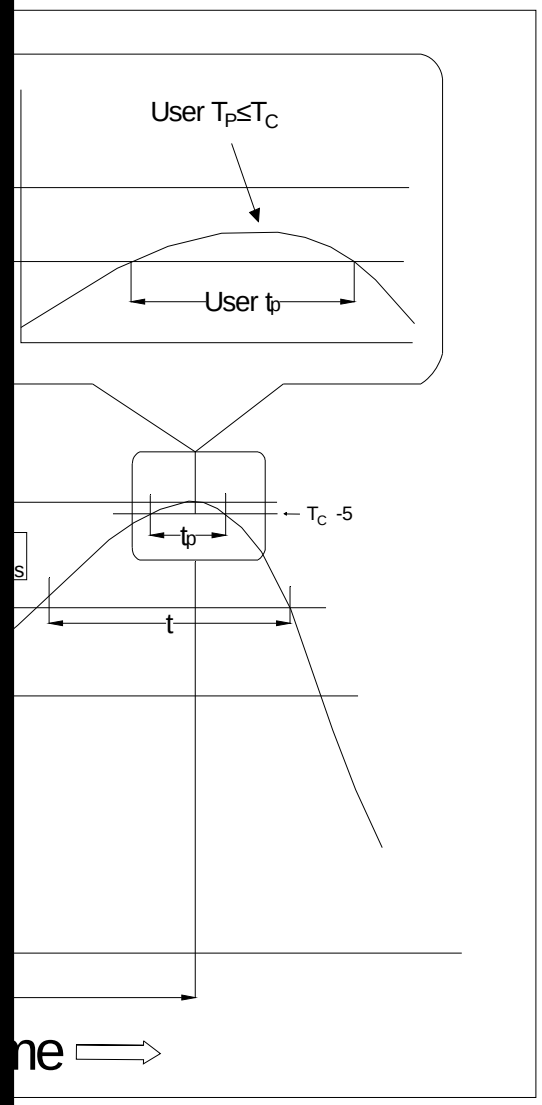


FIG.8: Propagation Delay vs. Ambient Temperature

Option None





y Profile	Pb-Free Assembly Profile

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.